

### **AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions and listings of claims in the application:

#### **Listing of Claims:**

Claim 1 (Currently amended) ~~A method for transporting a device to prevent radiant thermal energy absorption by a surface which comprises the step of using a transporting transfer member~~ comprising:

- a) a body having a carbon-fiber reinforced composite material, said body having a top surface and a bottom surface;
- b) a metal film covering the top and bottom surfaces of the composite body, said film forming a reflective surface; and
- c) a glass fiber epoxy resin forming a layer on the metal film covering the top surface and the bottom surface of the body; and
- d) at least one electroconductive polymer part electrically connected to at least a part of one or more carbon fibers of said carbon-fiber reinforced composite material.

Claim 2 (Currently amended) ~~The method-transfer member~~ of Claim 1, wherein the glass fiber epoxy resin layer provides a protective cover for the metal film on the top and bottom surfaces of the body.

Claim 3 (Currently amended) ~~The method-transfer member~~ of Claim 1, wherein the reflective surface prevents the absorption of thermal energy by ~~a heat sensitive material or device~~ a device being transferred by said transfer member.

Claim 4 (Cancelled)

Claim 5 (Currently amended) ~~The method-transfer member~~ of Claim 1 or 3, wherein the metal film comprises at least one of titanium, copper, aluminum, steel, gold, silver, nickel, tin, and combinations thereof.

Claim 6 (Currently amended) The ~~method~~transfer member of Claim 1, wherein said carbon-fiber-reinforced composite of said body comprises a non purity of less than 30 ppm water and less than 5 ppm hydrogen gas being evolved at a vacuum of  $10^{-5}$  Pa, having a temperature condition from 25°C to 250°C at a ramp up rate of 10°C/min.

Claim 7 (Currently amended) The ~~method~~transfer member of Claim 1, wherein said glass fiber epoxy resin comprises a combination of a glass fiber material and an epoxy material.

Claim 8 (Currently amended) The ~~method~~transfer member of Claim 7, wherein said glass fiber material is selected from the group consisting of S-glass, E-glass, and D-glass.

Claim 9 (Currently amended) The ~~method~~transfer member of Claim 7, wherein said epoxy resin material comprises condensation products of epichlorohydrin and bisphenol-A.

Claim 10 (Currently amended) The ~~method~~transfer member of Claim 1, wherein ~~the transfer member comprises three layers forming a composite body and~~ said body comprises three layers, each layer of the composite body preferably ranges having a thickness in the range of from about 0.02 mm to about 1.00 mm ~~in thickness~~.

Claim 11 (New) The transfer member of Claim 1, wherein at least a portion of said electroconductive polymer part is in direct or indirect contact with a device being transferred by said transfer member.

Claim 12 (New) The transfer member of Claim 11, wherein said electroconductive polymer part is electrically connected to a grounding conductor by at least a portion of said carbon fibers of said carbon-fiber reinforced composite material.

Claim 13 (New) The transfer member of Claim 1, wherein said electroconductive polymer part comprises a thermosetting or thermoplastic polymer and an electroconductive filler added thereto.

Claim 14 (New) The transfer member of Claim 13, wherein said thermosetting or thermoplastic polymer comprises one or more polymers selected from the group consisting of polyimide, fluoropolymer, polyamideimide, polyamide, polyetherimide, polyoxymethylene, polyetheretherketone, polyetherketoneketone, polyetherketone, polyacetate, nylon polymer, aromatic polyimide, polyethersulfone, polyimide polyetherimide, polyester, liquid crystal polymer, polybenzimidazole, poly(paraphenylene benzobisaxazole), polyphenylene sulfide, polycarbonate, polyacrylate, and polyacetal.

Claim 15 (New) The transfer member of Claim 13, wherein said thermosetting or thermoplastic polymer is polyimide polymer.

Claim 16 (New) The transfer member of Claim 13, wherein said electroconductive filler comprises one or more materials selected from the group consisting of metal powders, carbon black, carbon fibers, zinc oxide, titanium oxide, and potassium titanate.

Claim 17 (New) The transfer member of Claim 1, wherein said carbon-fiber reinforced composite material comprises at least one layer of a cloth prepreg containing carbon fibers and at least one layer of a unidirectional prepreg containing carbon fibers, and wherein said body of said transfer member comprises a longitudinal direction with said carbon fibers of said unidirectional prepreg arranged essentially parallel to said longitudinal direction of said body.

Claim 18 (New) The transfer member of Claim 1, wherein said carbon-fiber reinforced composite material comprises a matrix, said matrix comprising one or more materials selected from the group consisting of a thermosetting polymer, including epoxy, aramid, bismaleimide, phenol, furan, urea, unsaturated polyester, epoxy acrylate, diallyl phthalate, vinyl ester, thermosetting polyimide,

and melamine; a thermoplastic polymer, including polyimide resin, nylon, liquid aromatic polyamide, polyester, liquid aromatic polyester, polypropylene, polyether sulfone polymer, polyphenylene sulfide, polyetheretherketone, polyetherketone, polyetherketoneketone, liquid crystal polymer, polysulfone, polyvinylchloride, vinylon, aramid, and fluoropolymer; carbon; a ceramic material, including alumina, silica, titanium carbide, silicon carbide, boron nitride, and silicon nitride; and a metal material, including titanium, aluminum, tin, silicon, copper, iron, magnesium, chromium, nickel, molybdenum, tungsten, and alloys thereof.

Claim 19 (New) A method of transporting a device which prevents radiant thermal energy absorption by a surface of said device, said method comprising transporting said device using the transfer member of Claim 1.

Claim 20 (New) The method of Claim 19 wherein said device is a flat panel display.